2SD1824

Silicon NPN epitaxial planar type

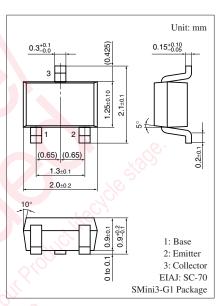
For low-frequency amplification

Features

- High forward current transfer ratio h_{FE}
- Low collector-emitter saturation voltage V_{CE(sat)}
- High emitter-base voltage (Collector open) V_{EBO}
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

Absolute Maximum Ratings $T_a = 25$ C						
Parameter	Symbol	Rating	Unit			
Collector-base voltage (Emitter open)	V _{CBO}	100	V			
Collector-emitter voltage (Base open)	V _{CEO}	100	V			
Emitter-base voltage (Collector open)	V _{EBO}	15	V			
Collector current	I _C	20	mA			
Peak collector current	I _{CP}	50	mA			
Collector power dissipation	P _C	150	mW			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C ₀			
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#### Marking symbol: 1V

### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

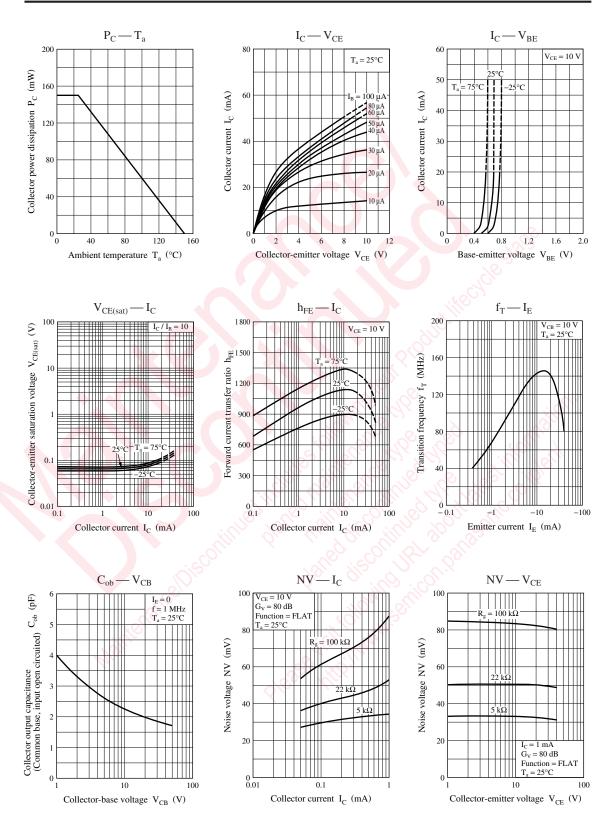
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$	100			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$	100			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, I_{\rm C} = 0$	15			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 60 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 60 \text{ V}, I_B = 0$			1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$	400		1 200	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$		0.05	0.20	V
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		90		MHz

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	S
$h_{\rm FE}$	400 to 800	600 to 1 200

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